

VERSIONS WITH MARKING TO SHOW CHANGES MADE

In the Specification

The paragraph beginning at line 21 of page 8 has been amended as follows:

Additional layers of material 140 may be coupled to the insulator layer 110 in order to continue building a layered component or printed circuit board 5. It is contemplated that the additional layers 140 will comprise materials similar to those already described herein, such as metal layer 142, including metals, metal alloys, composite materials, polymers, monomers, organic compounds, inorganic compounds, organometallic compounds, resins, adhesives and optical wave-guide materials.

In the Claims

1. An electronic component, comprising:
a substrate layer; and
an insulator layer coupled to the substrate layer, wherein the insulator layer comprises at ~~least two different kinds of embedded passive components~~ an insulating material, a first etched compartment filled with a capacitor material, and a second etched compartment filled with a resistor material, wherein the resistor material differs from the capacitor material and both the resistor material and capacitor material differ from the insulating material of the insulator layer.
11. The electronic component of claim 1, ~~wherein the at least two embedded passive components comprises a resistor and a capacitor~~ further comprising a first embedded passive component and a second embedded passive component wherein the first passive component is a resistor comprising the resistor material and the second passive component is a capacitor comprising the capacitor material.